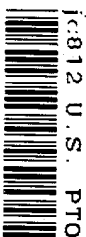


01/31/02



02-05-02



NON-PROVISIONAL APPLICATION FOR U. S. PATENT UNDER 37 CFR 1.53(b)

TRANSMITTAL FORM

Attorney Docket No. TI-33486

BOX PATENT APPLICATION
Assistant Commissioner for Patents
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the
patent application of:

"EXPRESS MAILING" Mailing Label No. EL915821608US
Date of Deposit January 31, 2002
I hereby certify that this paper is being deposited with the U.S. Postal Service
Express Mail Post Office to Addressee Service under 37 CFR 1.10 on the date
shown above and is addressed to the BOX PATENT APPLICATION, Assistant
Commissioner for Patents, Washington, D.C. 20231.

Trish Paramore

Inventor(s): Wee Lee Ng, et al

For: **IMPROVED PCB SOLDER PAD GEOMETRY INCLUDING PATTERNS
IMPROVING SOLDER COVERAGE**

Enclosed are:

6 Sheets of informal drawings and 15 pages of Specification (including Abstract)
X A Declaration/Power of Attorney
X Assignment with form PTO 1595

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 740.00
Total Claims	20	-20 =	0	X \$18 =	0.00
Independent Claims	3	-3 =	0	X \$84 =	0.00
Total Filing Fee					\$740.00

Please charge Deposit Account No. 20-0668 in the amount of the total fees set forth. The Assistant Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668.

All correspondence related to this application may be addressed to Mike Skrehot at Texas Instruments Incorporated, P. O. Box 655474, M/S 3999, Dallas, Texas 75265 and (972) 917-5653.

January 31, 2002

Dated

Robert C. Klinger
Reg. No. 34,365